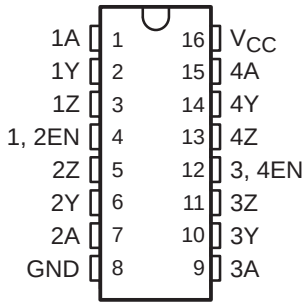
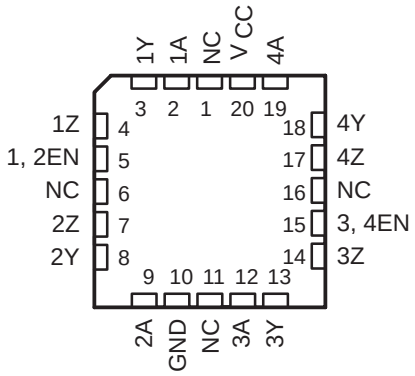
SLLS009D – OCTOBER 1985 – REVISED MAY 1995

- **Meet or Exceed the Requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11**
- **Designed to Operate Up to 20 Mbaud**
- **3-State TTL-Compatible Outputs**
- **Single 5-V Supply Operation**
- **High Output Impedance in Power-Off Condition**
- **Two Pairs of Drivers, Independently Enabled**
- **Designed as Improved Replacements for the MC3487**

SN55ALS194 . . . J OR W PACKAGE
SN75ALS194 . . . D OR N PACKAGE
(TOP VIEW)



SN55ALS194 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

These four differential line drivers are designed for data transmission over twisted-pair or parallel-wire transmission lines. They meet the requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11 and are compatible with 3-state TTL circuits. Advanced low-power Schottky technology provides high speed without the usual power penalty. Standby supply current is typically only 26 mA. Typical propagation delay time is less than 10 ns, and enable/disable times are typically less than 16 ns.

High-impedance inputs keep input currents low: less than 1 μA for a high level and less than 100 μA for a low level. The driver circuits can be enabled in pairs by separate active-high enable inputs. The SN55ALS194 and SN75ALS194 are capable of data rates in excess of 20 megabits per second and are designed to operate with the SN55ALS195 and SN75ALS195 quadruple line receivers.

The SN55ALS194 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN75ALS194 is characterized for operation from 0°C to 70°C.

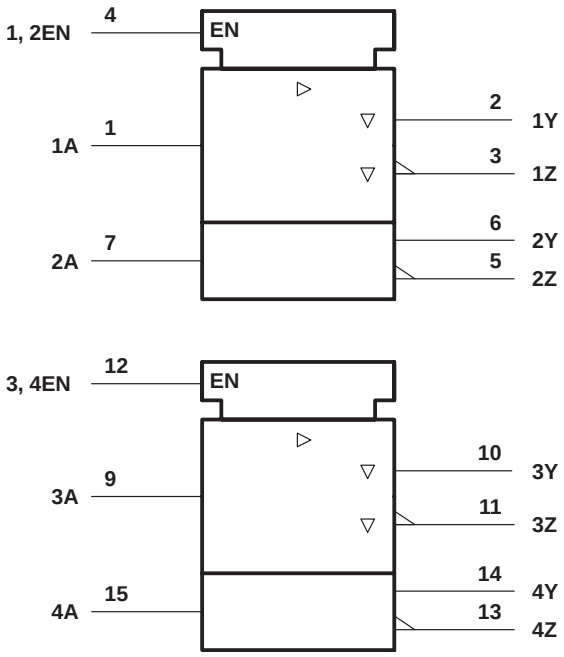
FUNCTION TABLE
(each driver)

INPUTS A	OUTPUT EN	OUTPUTS Y	OUTPUTS Z
H	H	H	L
L	H	L	H
X	L	Z	Z

H = high level, L = low level, X = irrelevant,
Z = high impedance

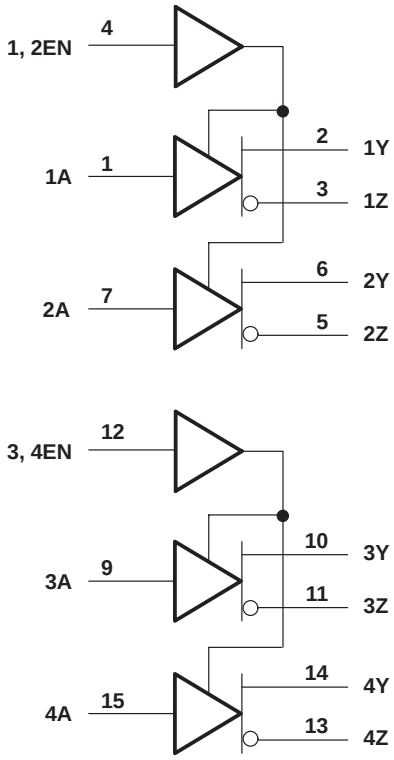
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

logic symbol†

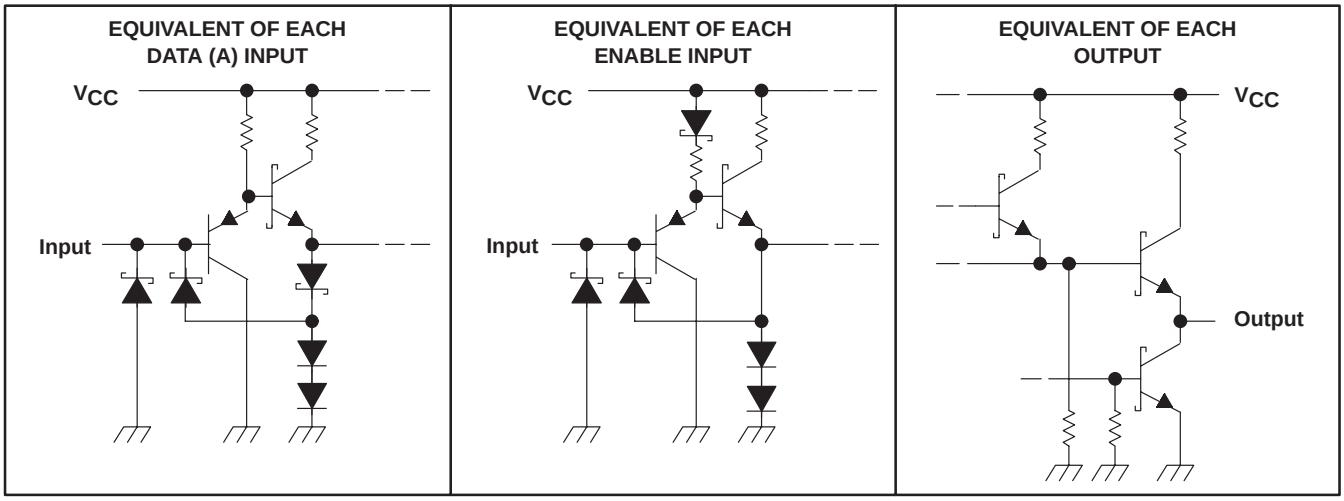


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, N, and W packages.

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I . . . . . 5.5 V
Output voltage, V_O . . . . . 7 V
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: SN55ALS194 . . . . . – 55°C to 125°C
SN75ALS194 . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . – 65°C to 150°C
Case temperature for 60 seconds, T_C: FK package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or W package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package . . . . . 300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW	N/A
FK	1375 mW	11.0 mW/°C	880 mW	275 mW
J	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	N/A
W	1000 mW	8.0 mW/°C	640 mW	200 mW

recommended operating conditions‡

		SN55ALS194			SN75ALS194			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level input voltage, V_{IH}	All inputs, T_A = 25°C	2			2			V
	A inputs, T_A = Full range	2			2			
	EN inputs, T_A = Full range	2.1			2			
Low-level input voltage, V_{IL}				0.8			0.8	V
High-level output current, I_{OH}				– 20			– 20	mA
Low-level output current, I_{OL}	T_A = 25°C			48			48	mA
	T_A = Full range			20			48	
Operating free-air temperature, T_A		– 55		125	0		70	°C

‡ Full range is T_A = – 55°C to 125°C for SN55ALS194 and T_A = 0°C to 70°C for SN75ALS194.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = –18 mA			– 1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, I_{OH} = –20 mA	SN55ALS194	2.4			V
			SN75ALS194	2.5			
V_{OL}	Low-level output voltage	V_{CC} = MIN,	I_{OL} = MAX			0.5	V
V_O	Output voltage	I_O = 0		0		6	V
$\|V_{OD1}\|$	Differential output voltage	I_O = 0		1.5		6	V
$\|V_{OD2}\|$	Differential output voltage	R_L = 100 Ω,	See Figure 1	1/2 V_{OD1} or 2§			V
$\Delta\|V_{OD}\|$	Change in magnitude of differential output voltage¶					± 0.4	V
V_{OC}	Common-mode output voltage					± 3	V
$\Delta\|V_{OC}\|$	Change in magnitude of common-mode output voltage¶					± 0.4	V
I_O	Output current with power off	V_{CC} = 0	V_O = 6 V			100	µA
			V_O = – 0.25 V			– 100	
I_{OZ}	High-impedance-state output current	V_{CC} = MAX, Output enables at 0.8 V	V_O = 2.7 V			100	µA
			V_O = 0.5 V			– 100	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V			100	µA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			50	µA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.5 V			– 200	µA
I_{OS}	Short-circuit output current#	V_{CC} = MAX,	V_I = 2 V	– 40		– 140	mA
I_{CC}	Supply current (all drivers)	V_{CC} = MAX,	All outputs disabled		26	45	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, TA = 25°C.
§ The minimum V_{OD2} with a 100-Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.
¶ $\Delta|V_{OD}|$ and $\Delta|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
# Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	SN55ALS194			SN75ALS194			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 15 pF, See Figure 2		6	13		6	13	ns
t_{PHL}	Propagation delay time, high- to low-level output			9	14		9	14	ns
	Output-to-output skew			3.5	6		3.5	6	ns
$t_{t(OD)}$	Differential output transition time	C_L = 15 pF, See Figure 3		8	14		8	14	ns
t_{PZH}	Output enable time to high level	C_L = 15 pF, See Figure 4		9	12		9	12	ns
t_{PZL}	Output enable time to low level			12	20		12	20	ns
t_{PHZ}	Output disable time from high level			9	15		9	14	ns
t_{PLZ}	Output disable time from low level			12	15		12	15	ns

SYMBOL EQUIVALENTS

DATA SHEET PARAMETER	EIA/TIA-422-B
V_O	V_{oa}, V_{ob}
$\lvert V_{OD1} \rvert$	V_o
$\lvert V_{OD2} \rvert$	V_t (R_L = 100 Ω)
$\Delta \lvert V_{OD} \rvert$	$\lvert \lvert V_t \rvert - \lvert \overline{V}_t \rvert \rvert$
V_{OC}	$\lvert V_{os} \rvert$
$\Delta \lvert V_{OC} \rvert$	$\lvert V_{os} - \overline{V}_{os} \rvert$
I_{OS}	$\lvert I_{sa} \rvert$, $\lvert I_{sb} \rvert$
I_O	$\lvert I_{xa} \rvert$, $\lvert I_{xb} \rvert$

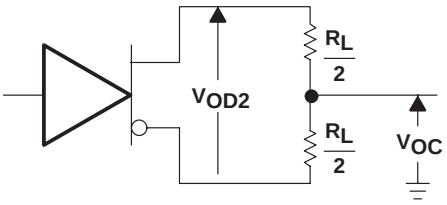
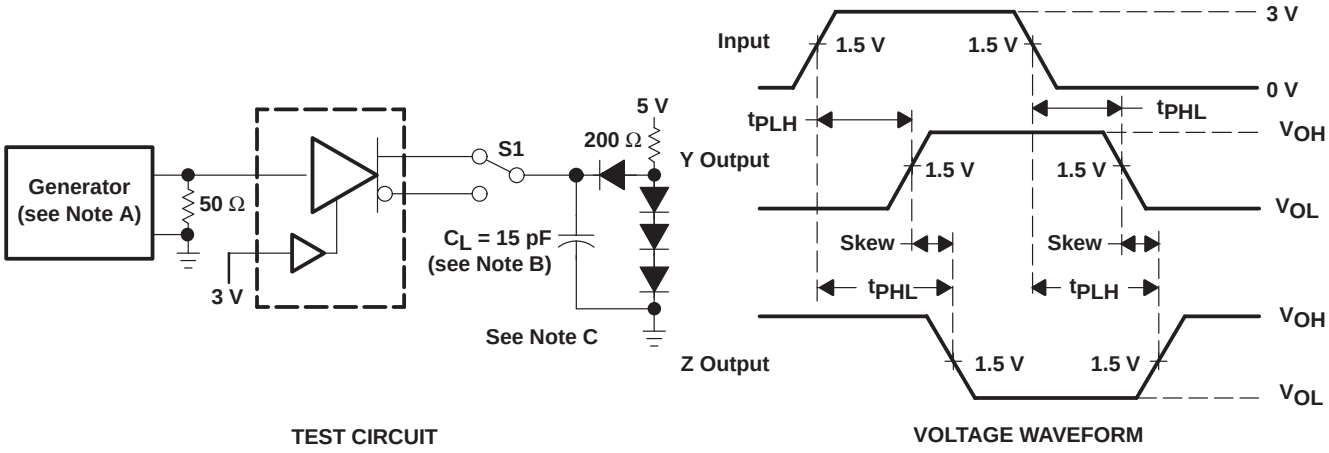


Figure 1. Driver V_{OD} and V_{OC}

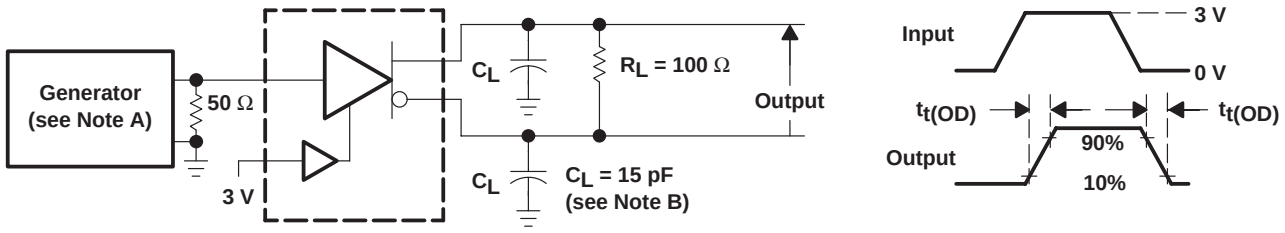
PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT **VOLTAGE WAVEFORM**

NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_r \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle ≤ 50%, $Z_O \approx 50\ \Omega$.
B. C_L includes probe and stray capacitance.
C. All diodes are 1N916 or 1N3064.

Figure 2. Test Circuit and Voltage Waveform

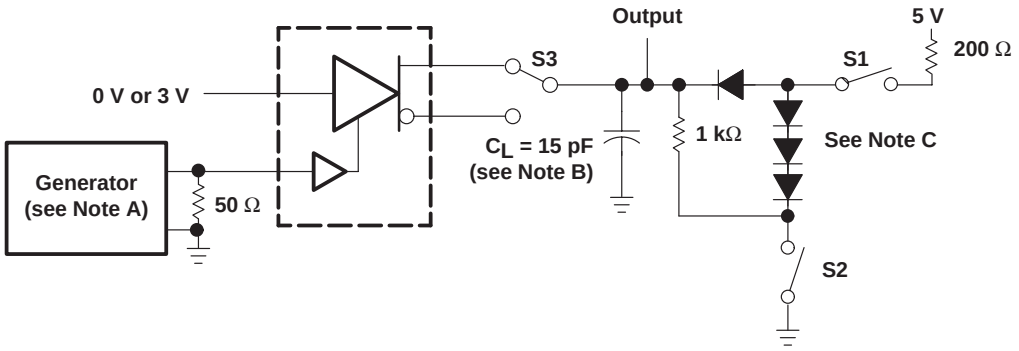


TEST CIRCUIT **VOLTAGE WAVEFORM**

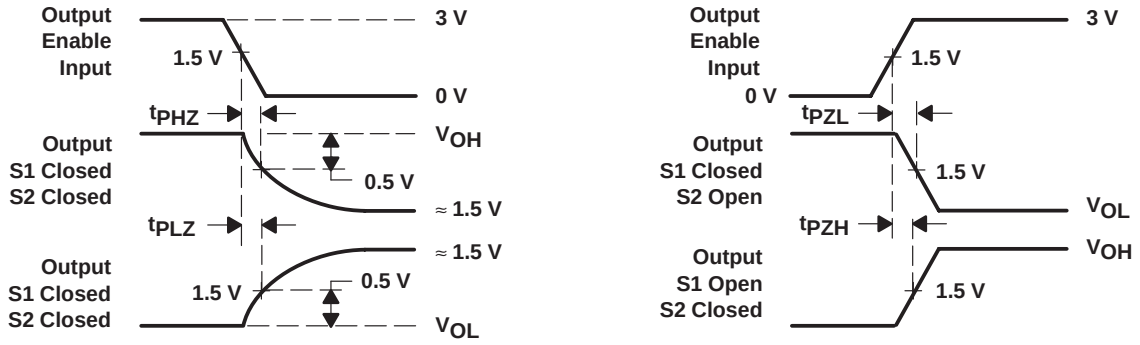
NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_r \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle ≤ 50%, $Z_O \approx 50\ \Omega$.
B. C_L includes probe and stray capacitance.

Figure 3. Differential-Output Test Circuit and Voltage Waveform

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_r \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle ≤ 50%, $Z_O \approx 50\ \Omega$.
B. C_L includes probe and stray capacitance.
C. All diodes are 1N916 or 1N3064.

Figure 4. Driver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS†

Y OUTPUT VOLTAGE vs DATA INPUT VOLTAGE

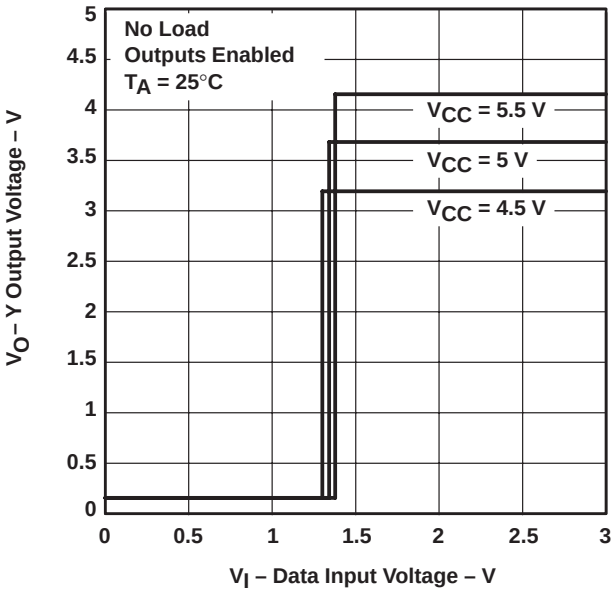


Figure 5

Y OUTPUT VOLTAGE vs DATA INPUT VOLTAGE

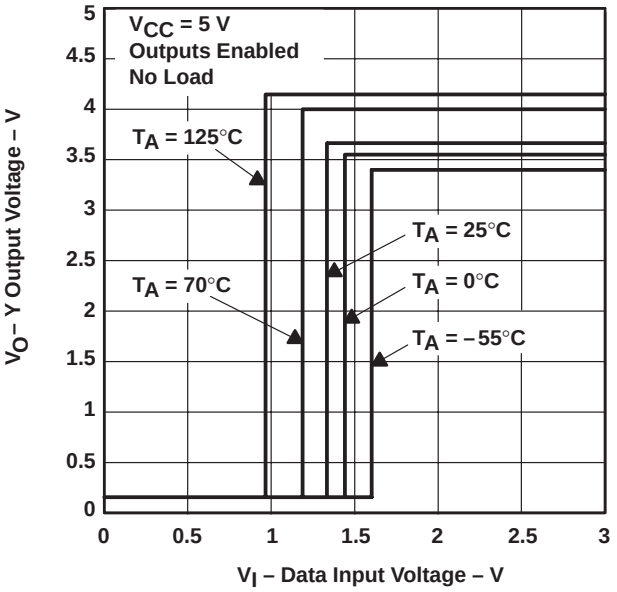


Figure 6

Y OUTPUT VOLTAGE vs ENABLE G INPUT VOLTAGE

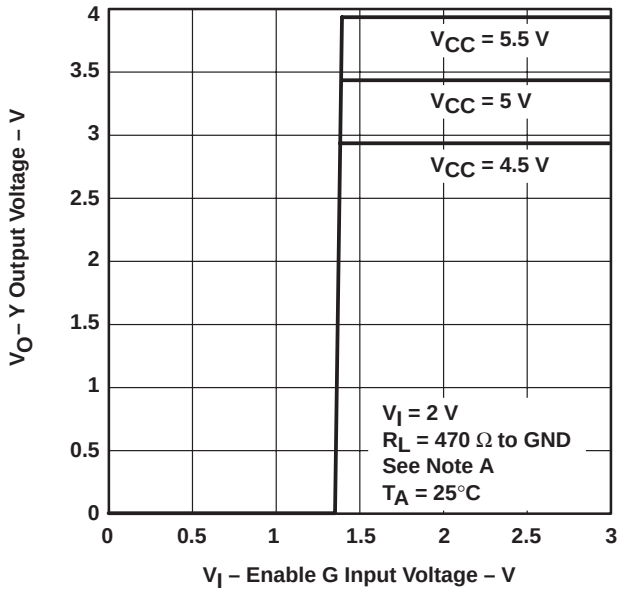


Figure 7

Y OUTPUT VOLTAGE vs ENABLE G INPUT VOLTAGE

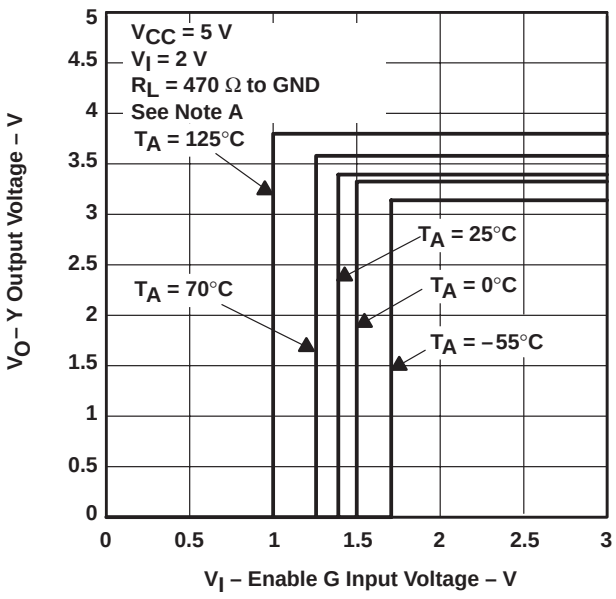


Figure 8

† Data for temperatures below 0°C and above 70°C are applicable to the SN55ALS194 circuits only.
NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to GND during the testing of the Z outputs.

TYPICAL CHARACTERISTICS†

Z OUTPUT VOLTAGE vs ENABLE G INPUT VOLTAGE

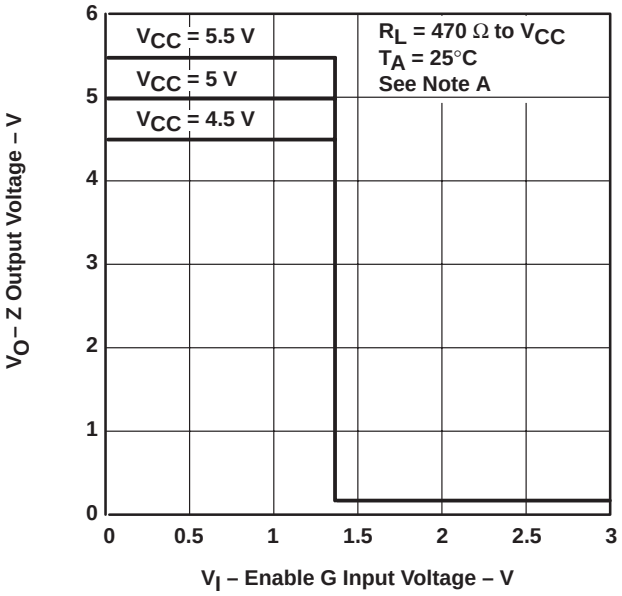


Figure 9

Z OUTPUT VOLTAGE vs ENABLE G INPUT VOLTAGE

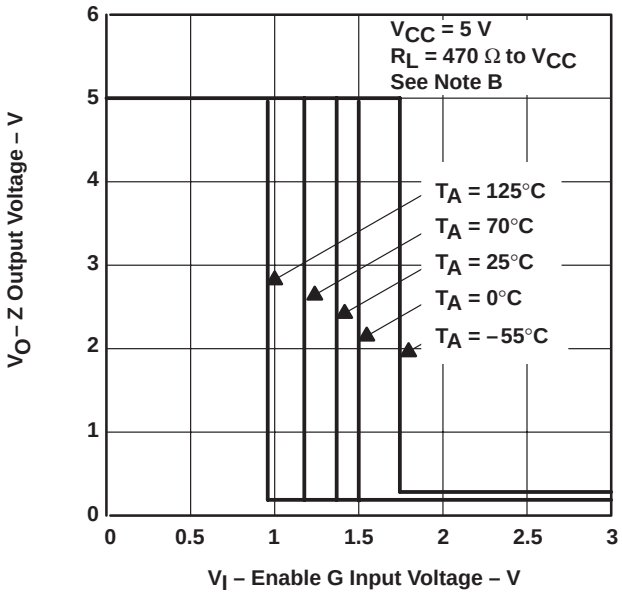


Figure 10

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

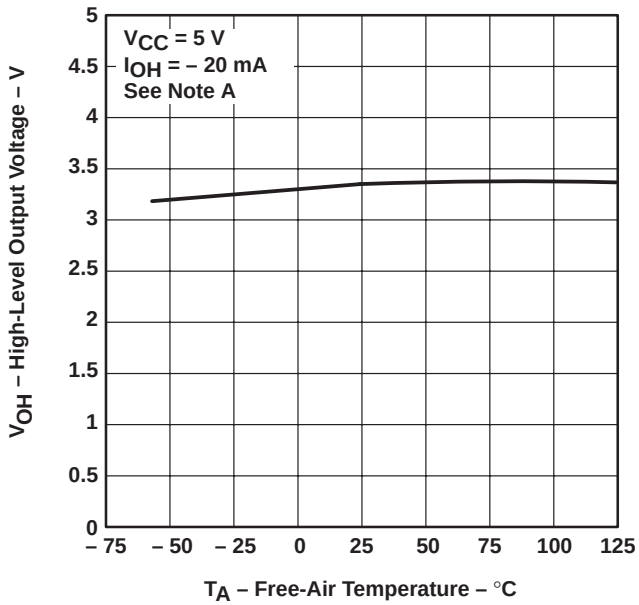


Figure 11

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

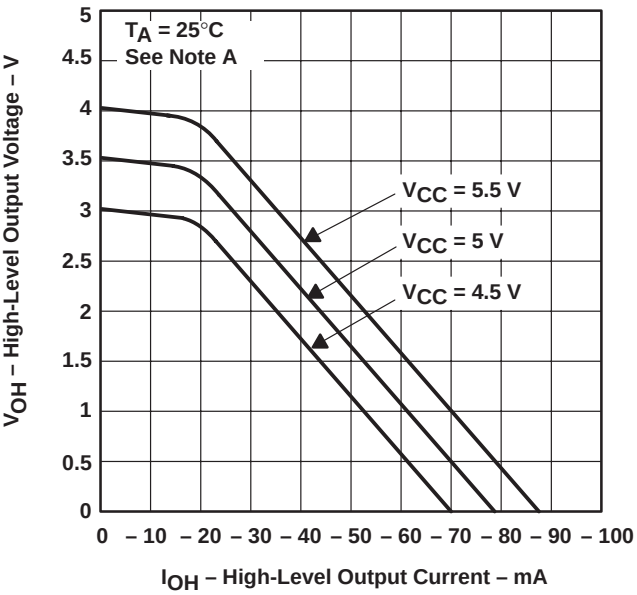


Figure 12

† Data for temperatures below 0°C and above 70°C are applicable to the SN55ALS194 circuits only.

NOTES: A. The A input is connected to V_{CC} during the testing of the Y outputs and to GND during the testing of the Z outputs.
B. The A input is connected to ground during the testing of the Y outputs and to V_{CC} during the testing of the Z outputs.

TYPICAL CHARACTERISTICS†

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

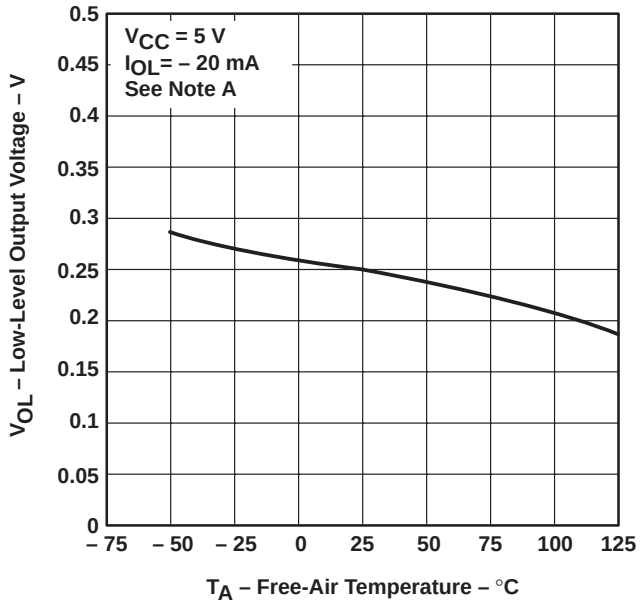


Figure 13

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

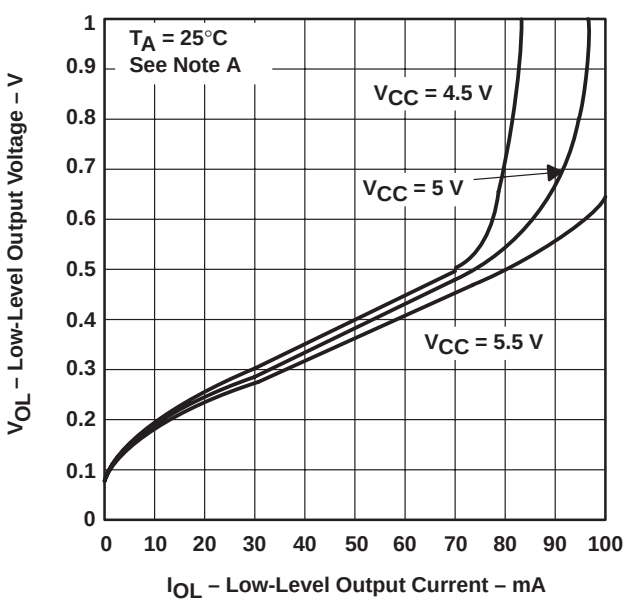


Figure 14

NOTE A: The A input is connected to GND during the testing of the Y outputs and to V_{CC} during the testing of the Z outputs.

SUPPLY CURRENT vs SUPPLY VOLTAGE

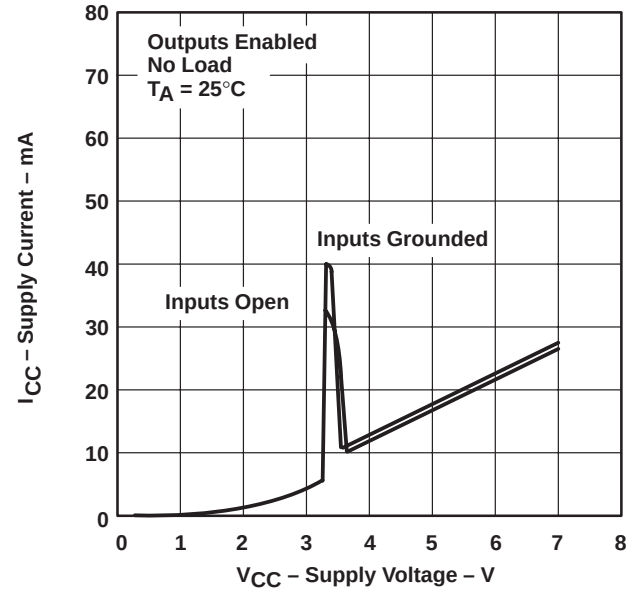


Figure 15

SUPPLY CURRENT vs SUPPLY VOLTAGE

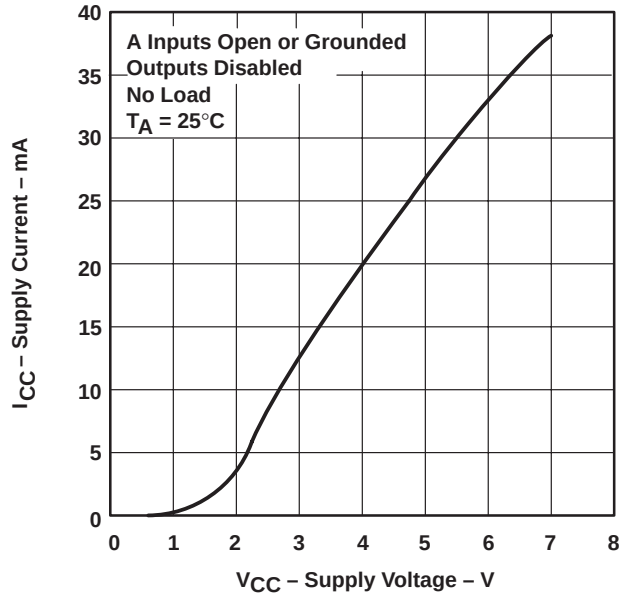


Figure 16

† Data for temperatures below 0°C and above 70°C are applicable to the SN55ALS194 circuits only.

TYPICAL CHARACTERISTICS

**SUPPLY CURRENT
vs
FREQUENCY**

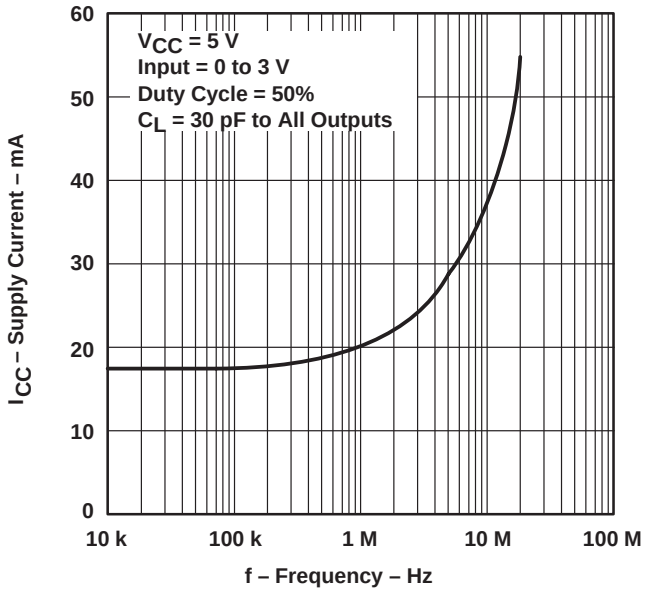


Figure 17

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75ALS194D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS194	Samples
SN75ALS194DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS194	Samples
SN75ALS194DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS194	Samples
SN75ALS194N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS194N	Samples
SN75ALS194NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS194N	Samples
SN75ALS194NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS194	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

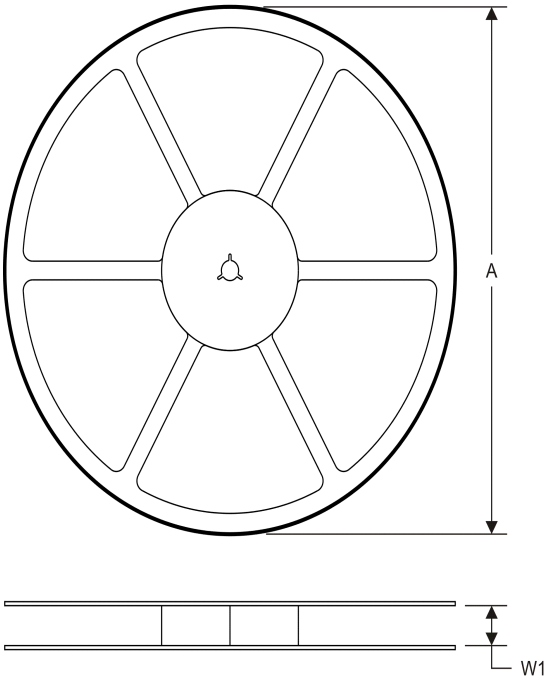
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

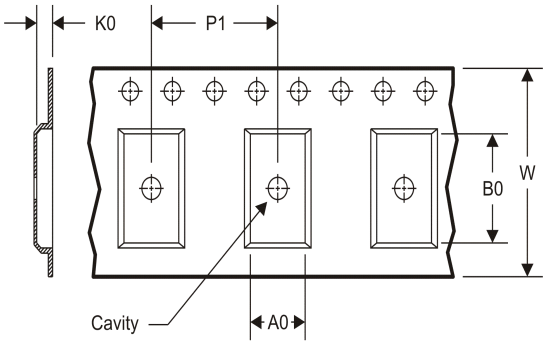
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



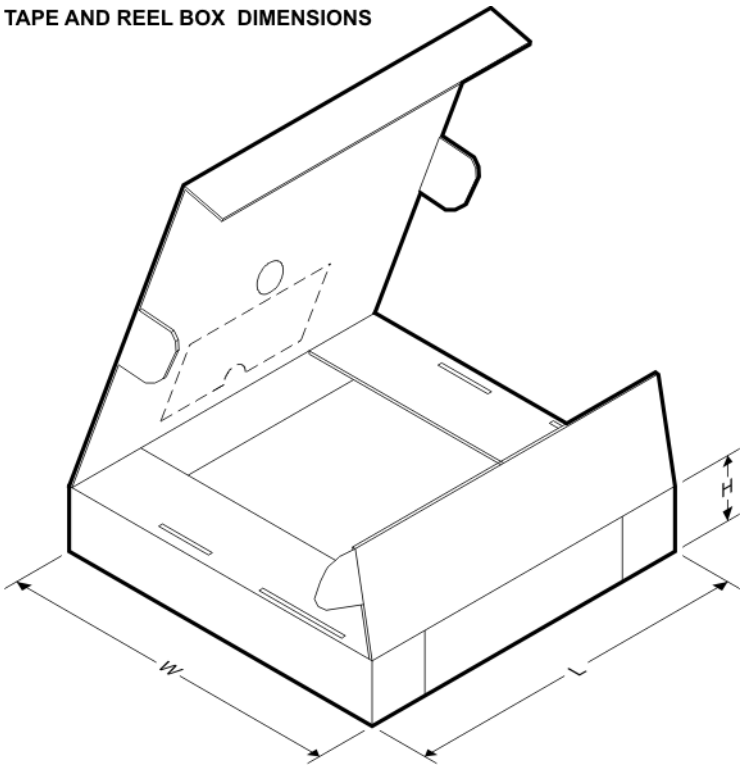
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS194DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75ALS194NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

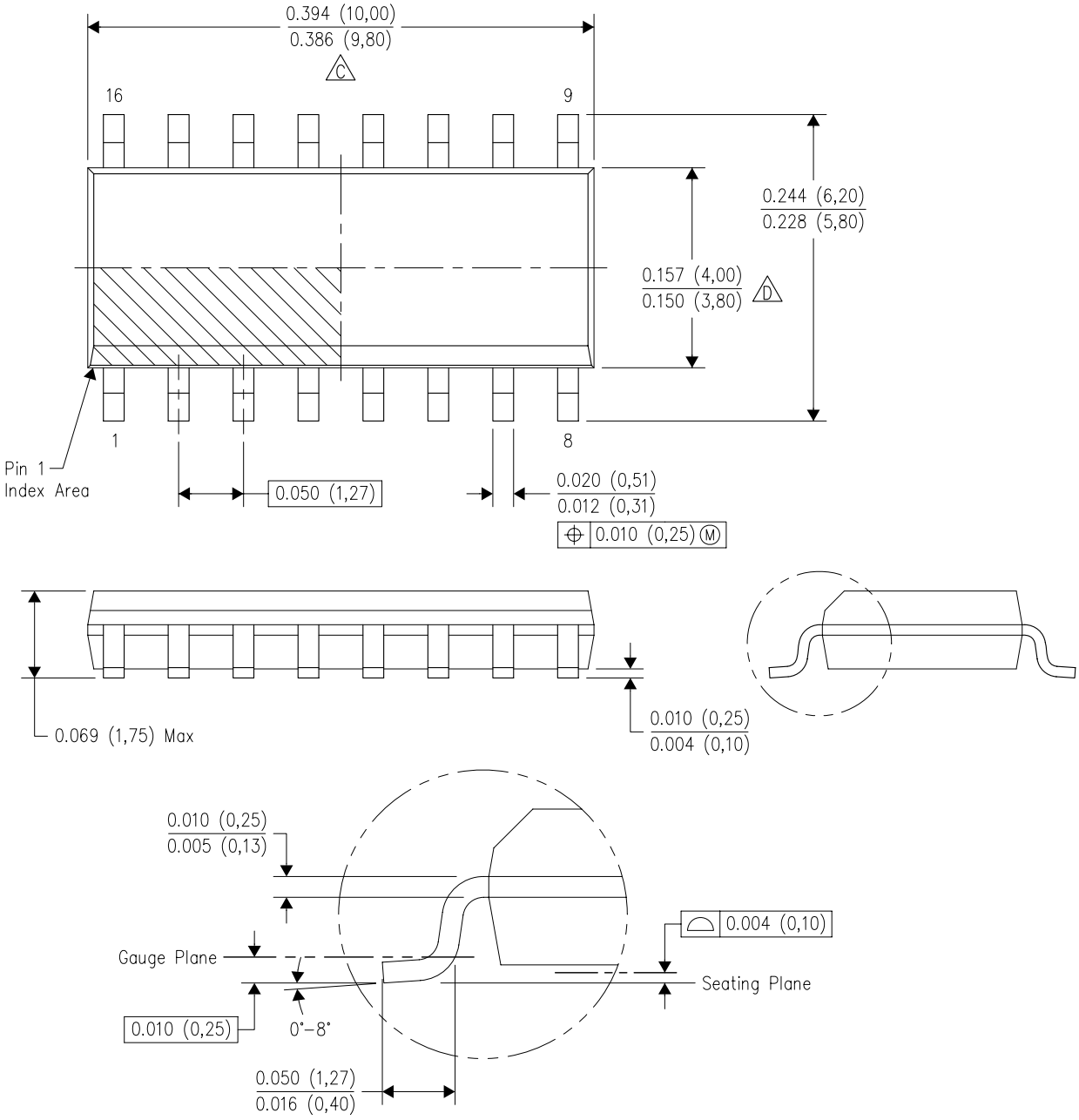
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

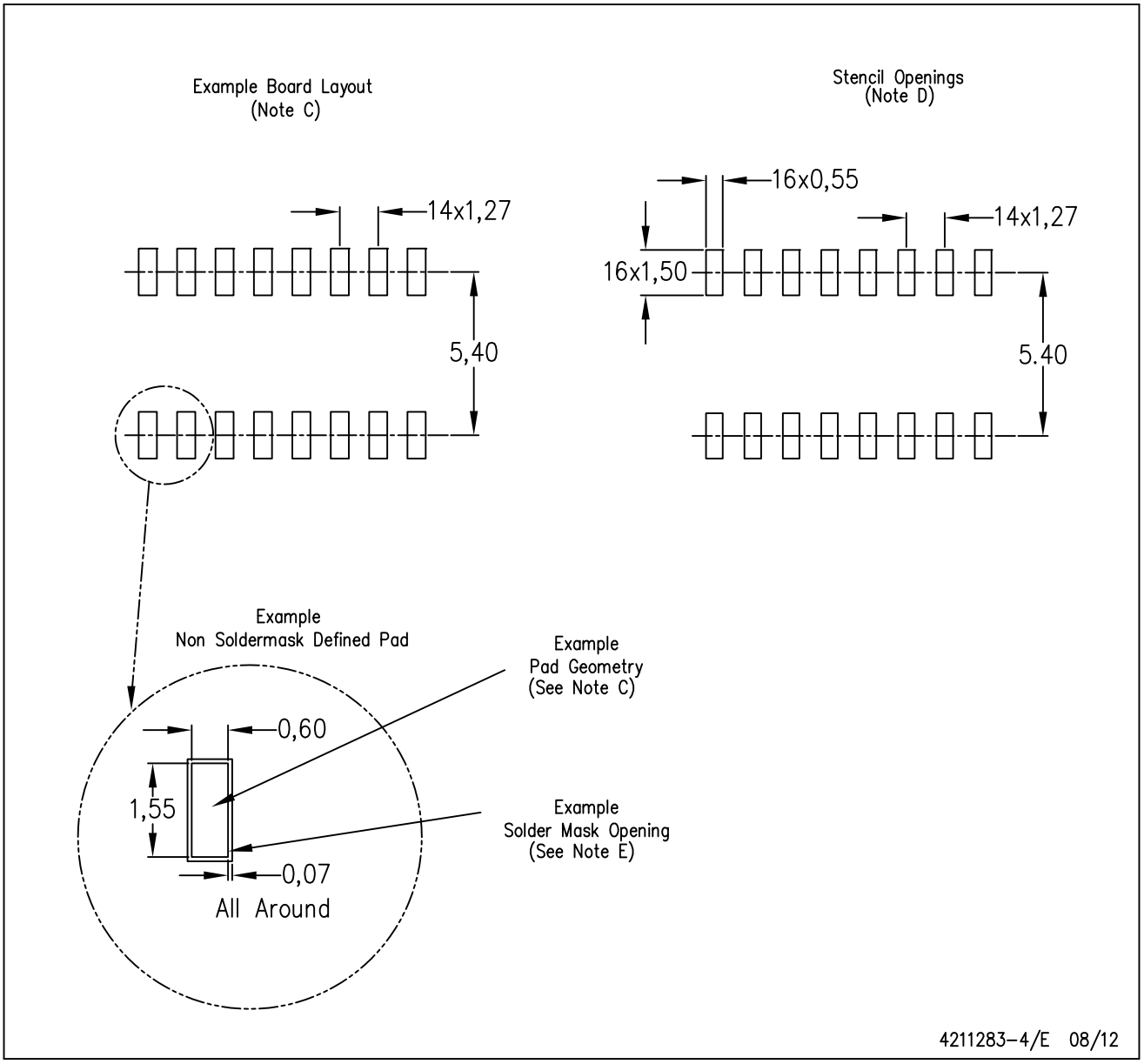
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS194DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75ALS194NSR	SO	NS	16	2000	367.0	367.0	38.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

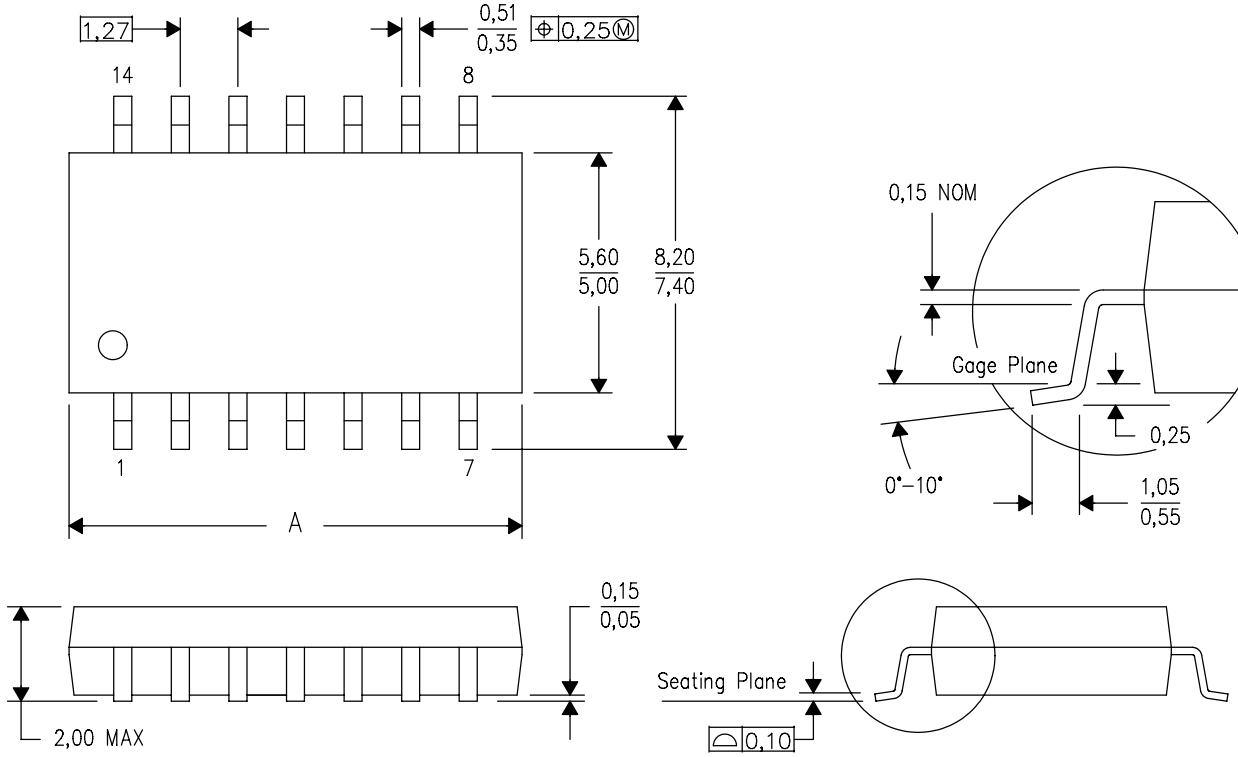


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

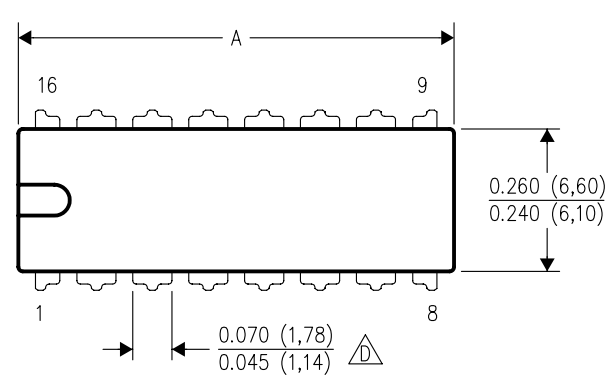
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

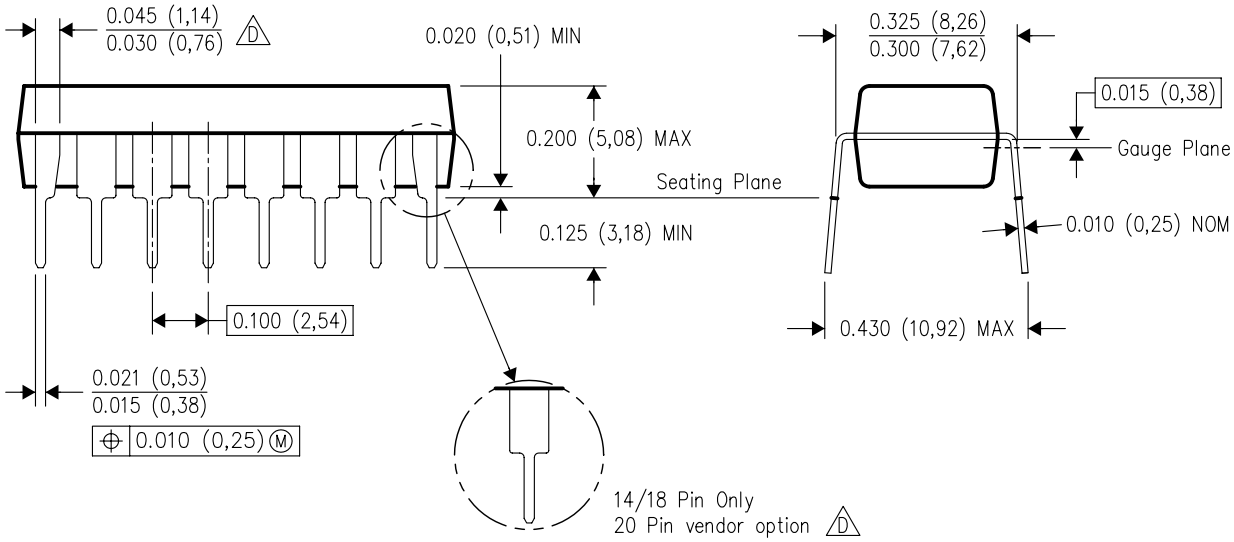
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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